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BASIC EMC PUBLICATION

Electromagnetic compatibility (EMC) – Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields

INTERNATIONAL ELECTROTECHNICAL COMMISSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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ELECTROMAGNETIC COMPATIBILITY (EMC) –

Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields

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This redline version of the official IEC Standard allows the user to identify the changes made to the previous edition IEC 61000-4-6:2013. A vertical bar appears in the margin wherever a change has been made. Additions are in green text, deletions are in ~~strikethrough red text~~.

IEC 61000-4-6 has been prepared by subcommittee 77B: High frequency phenomena, of IEC technical committee 77: Electromagnetic compatibility. It is an International Standard.

It forms Part 4-6 of IEC 61000. It has the status of a basic EMC publication in accordance with IEC Guide 107.

This fifth edition cancels and replaces the fourth edition published in 2013. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) selection of injection devices revised;
b) need of AE impedance check for clamp injection removed and Annex H deleted;
c) saturation check revised;
d) new Annex H on testing with multiple signals;
e) level-setting only with feedback loop.

The text of this International Standard is based on the following documents:

Draft	Report on voting
77B/863/FDIS	77B/865/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 61000 series, published under the general title *Electromagnetic compatibility (EMC)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The "colour inside" logo on the cover page of this document indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

IEC 61000 is published in separate parts according to the following structure:

Part 1: General

General considerations (introduction, fundamental principles)

Definitions, terminology

Part 2: Environment

Description of the environment

Classification of the environment

Compatibility levels

Part 3: Limits

Emission limits

Immunity limits (in so far as they do not fall under the responsibility of the product committees)

Part 4: Testing and measurement techniques

Measurement techniques

Testing techniques

Part 5: Installation and mitigation guidelines

Installation guidelines

Mitigation methods and devices

Part 6: Generic standards

Part 9: Miscellaneous

Each part is further subdivided into several parts, published either as international standards or as technical specifications or technical reports, some of which have already been published as sections. Others will be published with the part number followed by a dash and a second number identifying the subdivision (example: IEC 61000-6-1).

This part is an international standard which gives immunity requirements and test procedures related to conducted disturbances induced by radio-frequency fields.

ELECTROMAGNETIC COMPATIBILITY (EMC) –

Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields

1 Scope

This part of IEC 61000 relates to the conducted immunity requirements of electrical and electronic equipment to electromagnetic disturbances coming from intended radio-frequency (RF) transmitters in the frequency range 150 kHz up to 80 MHz.

NOTE 1 Product committees might decide to use the methods described in this document also for frequencies up to 230 MHz (see Annex B) although the methods and test instrumentation are intended to be used in the frequency range up to 80 MHz.

Equipment not having at least one conducting wire ~~and/~~or cable (such as mains supply, signal line or earth connection) which can couple the equipment to the disturbing RF fields is excluded from the scope of this document.

NOTE 2 Test methods are ~~defined~~ specified in this part of IEC 61000 to assess the effect that conducted disturbing signals, induced by electromagnetic radiation, have on the equipment concerned. The simulation and measurement of these conducted disturbances are not adequately exact for the quantitative determination of effects. The test methods ~~defined~~ specified are structured for the primary objective of establishing adequate repeatability of results at various facilities for quantitative analysis of effects.

The object of this document is to establish a common reference for evaluating the functional immunity of electrical and electronic equipment when subjected to conducted disturbances induced by RF fields. The test method in this document describes a consistent method to assess the immunity of an equipment or system against a ~~defined~~ specified phenomenon.

NOTE 3 As described in IEC Guide 107, this document is a basic EMC publication for use by product committees of the IEC. As also stated in Guide 107, the IEC product committees are responsible for determining whether this immunity test standard should be applied or not, and if applied, they are responsible for determining the appropriate test levels and performance criteria.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

~~IEC 60050 (all parts), *International Electrotechnical Vocabulary (IEV)* (available at <http://www.electropedia.org>)~~

CISPR 16-1-2, *Specification for radio disturbance and immunity measuring apparatus and methods – Part 1-2: Radio disturbance and immunity measuring apparatus – Coupling devices for conducted disturbance measurements*

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BASIC EMC PUBLICATION

Electromagnetic compatibility (EMC) – Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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ELECTROMAGNETIC COMPATIBILITY (EMC) –

Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields

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IEC 61000-4-6 has been prepared by subcommittee 77B: High frequency phenomena, of IEC technical committee 77: Electromagnetic compatibility. It is an International Standard.

It forms Part 4-6 of IEC 61000. It has the status of a basic EMC publication in accordance with IEC Guide 107.

This fifth edition cancels and replaces the fourth edition published in 2013. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) selection of injection devices revised;
b) need of AE impedance check for clamp injection removed and Annex H deleted;
c) saturation check revised;
d) new Annex H on testing with multiple signals;

e) level-setting only with feedback loop.

The text of this International Standard is based on the following documents:

Draft	Report on voting
77B/863/FDIS	77B/865/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 61000 series, published under the general title *Electromagnetic compatibility (EMC)*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The "colour inside" logo on the cover page of this document indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

INTRODUCTION

IEC 61000 is published in separate parts according to the following structure:

Part 1: General

General considerations (introduction, fundamental principles)

Definitions, terminology

Part 2: Environment

Description of the environment

Classification of the environment

Compatibility levels

Part 3: Limits

Emission limits

Immunity limits (in so far as they do not fall under the responsibility of the product committees)

Part 4: Testing and measurement techniques

Measurement techniques

Testing techniques

Part 5: Installation and mitigation guidelines

Installation guidelines

Mitigation methods and devices

Part 6: Generic standards

Part 9: Miscellaneous

Each part is further subdivided into several parts, published either as international standards or as technical specifications or technical reports, some of which have already been published as sections. Others will be published with the part number followed by a dash and a second number identifying the subdivision (example: IEC 61000-6-1).

This part is an international standard which gives immunity requirements and test procedures related to conducted disturbances induced by radio-frequency fields.

ELECTROMAGNETIC COMPATIBILITY (EMC) –

Part 4-6: Testing and measurement techniques – Immunity to conducted disturbances, induced by radio-frequency fields

1 Scope

This part of IEC 61000 relates to the conducted immunity requirements of electrical and electronic equipment to electromagnetic disturbances coming from intended radio-frequency (RF) transmitters in the frequency range 150 kHz up to 80 MHz.

NOTE 1 Product committees might decide to use the methods described in this document also for frequencies up to 230 MHz (see Annex B) although the methods and test instrumentation are intended to be used in the frequency range up to 80 MHz.

Equipment not having at least one conducting wire or cable (such as mains supply, signal line or earth connection) which can couple the equipment to the disturbing RF fields is excluded from the scope of this document.

NOTE 2 Test methods are specified in this part of IEC 61000 to assess the effect that conducted disturbing signals, induced by electromagnetic radiation, have on the equipment concerned. The simulation and measurement of these conducted disturbances are not adequately exact for the quantitative determination of effects. The test methods specified are structured for the primary objective of establishing adequate repeatability of results at various facilities for quantitative analysis of effects.

The object of this document is to establish a common reference for evaluating the functional immunity of electrical and electronic equipment when subjected to conducted disturbances induced by RF fields. The test method in this document describes a consistent method to assess the immunity of an equipment or system against a specified phenomenon.

NOTE 3 As described in IEC Guide 107, this document is a basic EMC publication for use by product committees of the IEC. As also stated in Guide 107, the IEC product committees are responsible for determining whether this immunity test standard should be applied or not, and if applied, they are responsible for determining the appropriate test levels and performance criteria.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

CISPR 16-1-2, *Specification for radio disturbance and immunity measuring apparatus and methods – Part 1-2: Radio disturbance and immunity measuring apparatus – Coupling devices for conducted disturbance measurements*